



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Yoshino, et al.

Serial No.: 09/909,013

Filed: 07/19/2001

For: Semiconductor Package Insulation Film and Manufacturing Method
Thereof

Conf. No.: 8724

Docket No.: TI-29448

Examiner: Geyer, Scott B.

Art Unit: 2829

Appeal Brief

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that this correspondence is being deposited
with the U.S. Postal Service as First Class Mail in an
envelope addressed to: Commissioner for Patents, PO Box
1450, Alexandria, VA 22313-1450 on

September 8, 2003.

Elizabeth Austin
Elizabeth Austin

Dear Sir:

Pursuant to the Notice of Appeal mailed 07/08/03, Appellant submits this appeal brief in triplicate. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

Real Party in Interest

The real party in interest is Texas Instruments Incorporated.

Related Appeals and Interferences

No related appeals or interferences are known to Appellant.

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